

## 1.5A High-Speed 30V MOSFET Drivers

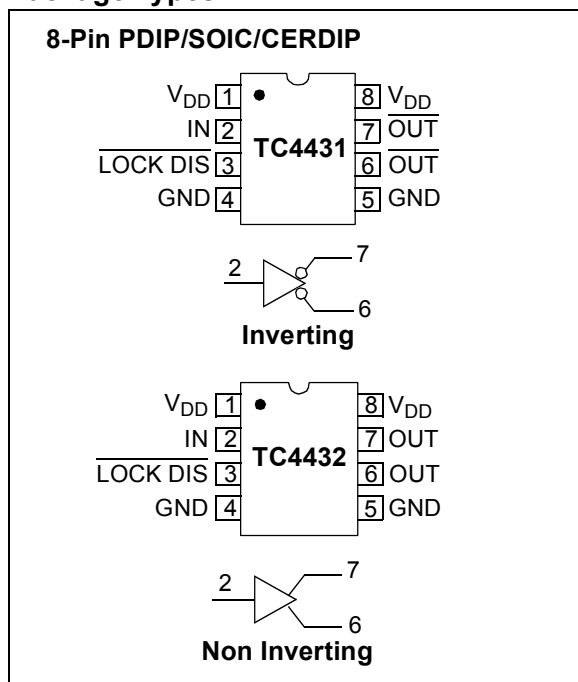
### Features

- High Peak Output Current – 1.5A
- Wide Input Supply Voltage Operating Range:
  - 4.5V to 30V
- High Capacitive Load Drive Capability:
  - 1000 pF in 25 nsec
- Short Delay Times – <78 nsec Typ.
- Low Supply Current:
  - With Logic '1' Input – 2.5 mA
  - With Logic '0' Input – 300  $\mu$ A
- Low Output Impedance – 7 $\Omega$
- Latch-Up Protected: Will Withstand >300 mA Reverse Current
- ESD Protected – 4 kV

### Applications

- Small Motor Drive
- Power MOSFET Driver
- Driving Bipolar Transistors

### Package Types



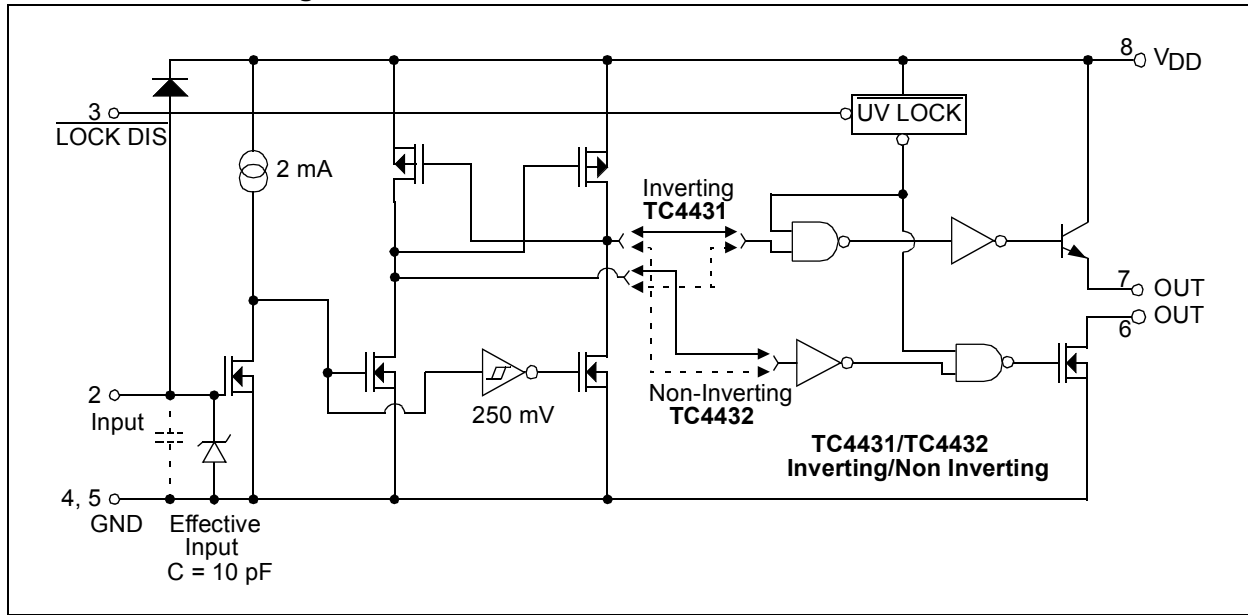
### General Description

The TC4431/TC4432 are 30V CMOS buffer/drivers suitable for use in high-side driver applications. They will not latch-up under any conditions within their power and voltage ratings. They can accept, without damage or logic upset, up to 300 mA of reverse current (of either polarity) being forced back into their outputs. All terminals are fully protected against up to 4 kV of electrostatic discharge.

Undervoltage lockout circuitry forces the output to a 'low' state when the input supply voltage drops below 7V. For operation at lower voltages, disable the lockout and start-up circuit by grounding pin 3 (LOCK DIS); for all other situations, pin 3 should be left floating. The under-voltage lockout and start-up circuit gives brown-out protection when driving MOSFETS.

# TC4431/TC4432

## Functional Block Diagram



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings†

Supply Voltage .....	36V
Input Voltage (Note 1).....	$V_{DD} + 0.3V$ to GND
Package Power Dissipation ( $T_A \leq 70^\circ C$ )	
PDIP .....	730 mW
CERDIP .....	800 mW
SOIC.....	470 mW
Maximum Junction Temperature, $T_J$ .....	+150°C
Storage Temperature Range.....	-65°C to +150°C

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

### DC CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, $T_A = +25^\circ C$ with $4.5V \leq V_{DD} \leq 30V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Input</b>						
Logic '1', High Input Voltage	$V_{IH}$	2.4	—	—	V	
Logic '0', Low Input Voltage	$V_{IL}$	—	—	0.8	V	
Input Current (Note 1)	$I_{IN}$	-1	—	1	$\mu A$	$0V \leq V_{IN} \leq 12V$
<b>Output</b>						
High Output Voltage	$V_{OH}$	$V_{DD} - 1.0$	$V_{DD} - 0.8$	—	V	$I_{OUT} = 100$ mA
Low Output Voltage	$V_{OL}$	—	—	0.025	V	
Output Resistance	$R_O$	—	7	10	$\Omega$	$I_{OUT} = 10$ mA, $V_{DD} = 30V$
Peak Output Current	$I_{PK}$	—	3.0	—	A	Source: $V_{DD} = 30V$ Sink: $V_{DD} = 30V$
Latch-Up Protection Withstand Reverse Current	$I_{REV}$	—	0.3	—	A	Duty cycle $\leq 2\%$ , $t \leq 300$ $\mu sec$
<b>Switching Time (Note 2)</b>						
Rise Time	$t_R$	—	25	40	nsec	Figure 4-1
Fall Time	$t_F$	—	33	50	nsec	Figure 4-1
Delay Time	$t_{D1}$	—	62	80	nsec	Figure 4-1
Delay Time	$t_{D2}$	—	78	90	nsec	Figure 4-1
<b>Power Supply</b>						
Power Supply Current	$I_S$	—	2.5	4	mA	$V_{IN} = 3V$ $V_{IN} = 0V$
Start-up Threshold	$V_S$	—	8.4	10	V	
Drop-out Threshold	$V_{DO}$	7	7.7	—	V	Note 3

**Note 1:** For inputs  $>12V$ , add a 1 k $\Omega$  resistor in series with the input. See "Typical Characteristics" graph for input current.

**2:** Switching times are ensured by design.

**3:** For operation below 7V, pin 3 (LOCK DIS) should be tied to ground to disable the lockout and start-up circuit, otherwise, pin 3 **must** be left floating.

# TC4431/TC4432

## DC CHARACTERISTICS (Continued)

Electrical Specifications: Unless otherwise noted, Over operating temperature range with $4.5V \leq V_{DD} \leq 30V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Input</b>						
Logic '1', High Input Voltage	$V_{IH}$	2.4	—	—	V	
Logic '0', Low Input Voltage	$V_{IL}$	—	—	0.8	V	
Input Current (Note 1)	$I_{IN}$	-10	—	10	$\mu A$	$0V \leq V_{IN} \leq 12V$
<b>Output</b>						
High Output Voltage	$V_{OH}$	$V_{DD} - 1.2$	—	—	V	$I_{OUT} = 100 \text{ mA}$
Low Output Voltage	$V_{OL}$	—	—	0.025	V	
Output Resistance	$R_O$	—	—	12	$\Omega$	$I_{OUT} = 10 \text{ mA}, V_{DD} = 30V$
<b>Switching Time (Note 2)</b>						
Rise Time	$t_R$	—	—	60	nsec	Figure 4-1
Fall Time	$t_F$	—	—	70	nsec	Figure 4-1
Delay Time	$t_{D1}$	—	—	100	nsec	Figure 4-1
Delay Time	$t_{D2}$	—	—	110	nsec	Figure 4-1
<b>Power Supply</b>						
Power Supply Current	$I_S$	—	—	6 0.7	mA	$V_{IN} = 3V$ $V_{IN} = 0V$
Start-up Threshold	$V_S$	—	8.4	10	V	
Drop-out Threshold	$V_{DO}$	7	7.7	—	V	Note 3

**Note 1:** For inputs >12V, add a 1 k $\Omega$  resistor in series with the input. See "Typical Characteristics" graph for input current.

**2:** Switching times are ensured by design.

**3:** For operation below 7V, pin 3 ( $\overline{\text{LOCK DIS}}$ ) should be tied to ground to disable the lockout and start-up circuit, otherwise, pin 3 **must** be left floating.

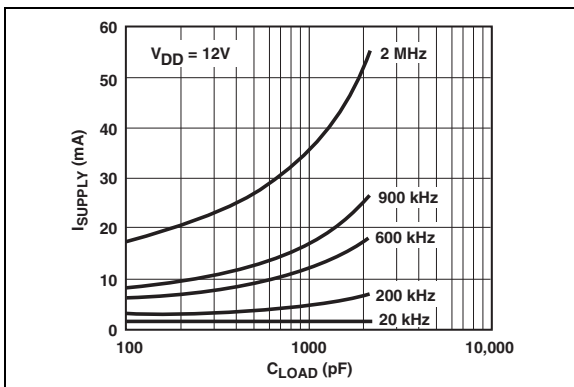
## TEMPERATURE CHARACTERISTICS

Electrical Specifications: Unless otherwise noted, all parameters apply with $4.5V \leq V_{DD} \leq 30V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Temperature Ranges</b>						
Specified Temperature Range (C)	$T_A$	0	—	+70	$^{\circ}C$	
Specified Temperature Range (E)	$T_A$	-40	—	+85	$^{\circ}C$	
Maximum Junction Temperature	$T_J$	—	—	+150	$^{\circ}C$	
<b>Storage Temperature Range</b>	$T_A$	-65	—	+150	$^{\circ}C$	
<b>Package Thermal Resistances</b>						
Thermal Resistance, 8L-SOIC	$\theta_{JA}$	—	155	—	$^{\circ}C/W$	
Thermal Resistance, 8L-PDIP	$\theta_{JA}$	—	125	—	$^{\circ}C/W$	
Thermal Resistance, 8L-CERDIP	$\theta_{JA}$	—	150	—	$^{\circ}C/W$	

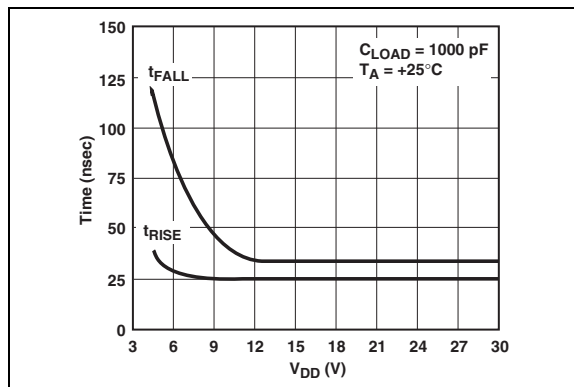
## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

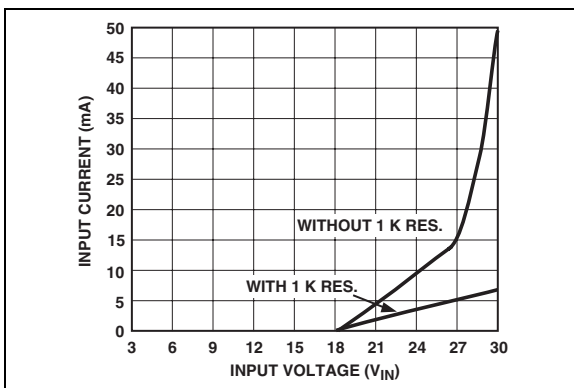
**Note:** Unless otherwise indicated,  $T_A = +25^\circ\text{C}$  with  $4.5\text{V} \leq V_{DD} \leq 30\text{V}$ .



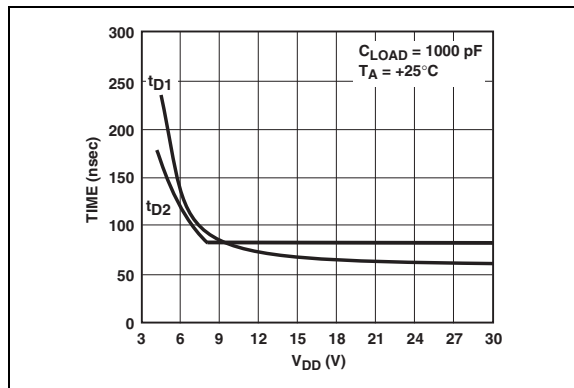
**FIGURE 2-1:** Supply Current vs. Capacitive Load.



**FIGURE 2-3:** Rise/Fall Time vs.  $V_{DD}$ .



**FIGURE 2-2:** Input Current vs. Input Voltage.



**FIGURE 2-4:**  $t_{D1}$  and  $t_{D2}$  Delay vs.  $V_{DD}$ .

# TC4431/TC4432

## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

**TABLE 3-1: PIN FUNCTION TABLE**

Pin No.	Symbol	Description
1	$V_{DD}$	Supply Input, 4.5V to 30V
2	IN	TTL/CMOS Compatible Input
3	$\overline{\text{LOCK DIS}}$	Input Pin, Enable/Disable for UV Lockout
4	GND	Ground
5	GND	Ground
6	OUT	Drive Output, Pull Down
7	OUT	Drive Output, Pull Up
8	$V_{DD}$	Supply Input, 4.5V to 30V

### 3.1 Supply Input ( $V_{DD}$ )

The  $V_{DD}$  input is the bias supply input for the MOSFET driver and is rated for 4.5V to 30V with respect to the ground pins. The  $V_{DD}$  input should be bypassed to ground with a local ceramic capacitor. The value of this capacitor should be chosen based on the capacitive load that is being driven.

### 3.2 Control Input (IN)

The MOSFET driver input is a TTL/CMOS compatible input with 250 mV of hysteresis between the high and low threshold voltages. If an input signal level of greater than 12V is applied to the device, a series current limiting resistor is recommended.

### 3.3 Lockout Disable ( $\overline{\text{LOCK DIS}}$ )

The lockout pin enables/disables the undervoltage lock-out feature of the device. If undervoltage lockout is desired (output is not enabled until the bias voltage reaches 8.4V (typical) on the rising edge and is disabled when the bias voltage reaches 7.7V (typical) on the falling edge), the lockout pin should be left floating. If operation below 7V is desired, the lockout pin should be tied to ground.

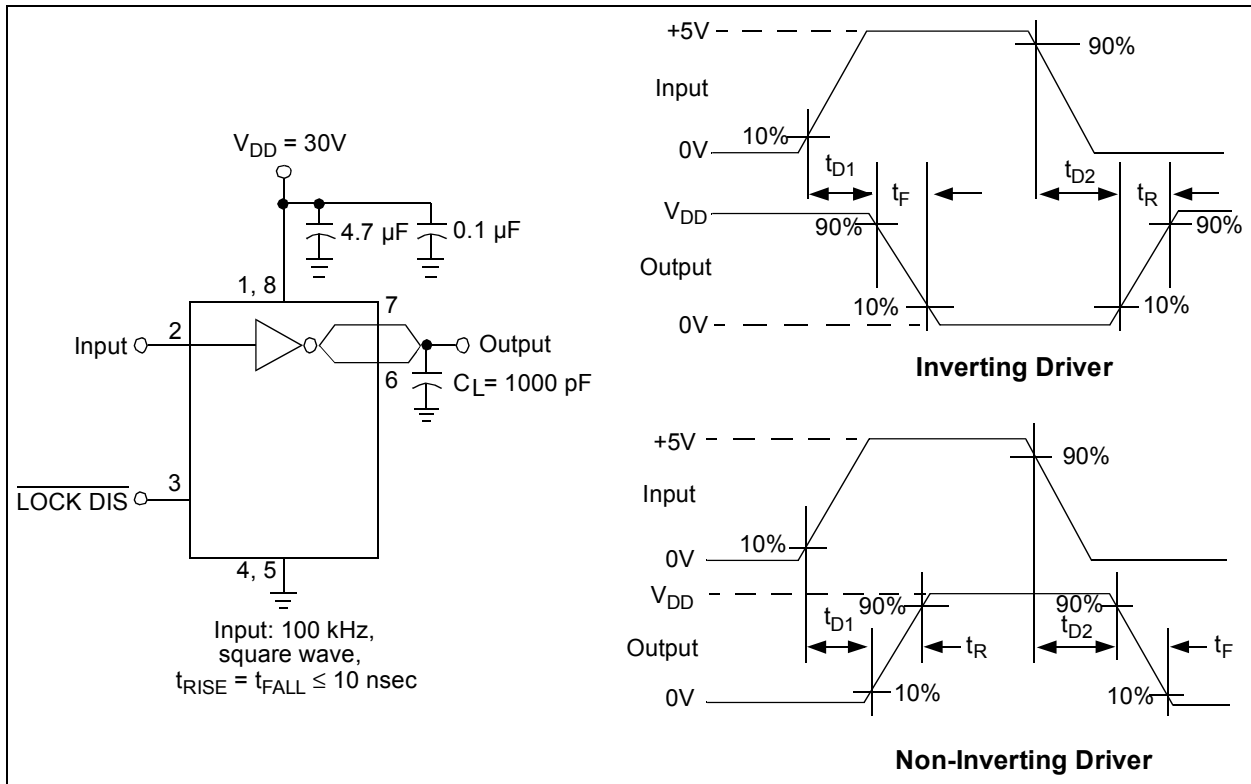
### 3.4 Ground (GND)

The ground pins are the return path for the bias current and for the high peak currents which discharge the load capacitor. Both ground pins should be used to ensure proper operation. The ground pins should be tied into a ground plane or have short traces to the bias supply source return.

### 3.5 Drive Output (OUT)

The TC4431/TC4432 devices have individual source and sink output pins. This feature can be used to adjust the rise and fall time independently by adding separate charge and discharge resistors external to the device. Pin 7 (source output) can source 3A peak currents into capacitive loads and pin 6 (sink output) can sink 1.5A peak currents from a capacitive load.

## 4.0 APPLICATIONS INFORMATION



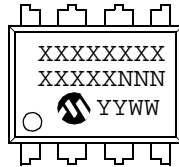
**FIGURE 4-1:** Switching Time Test Circuit.

# TC4431/TC4432

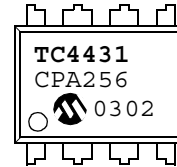
## 5.0 PACKAGING INFORMATION

### 5.1 Package Marking Information

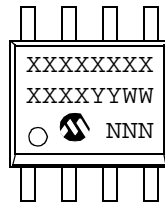
8-Lead PDIP (300 mil)



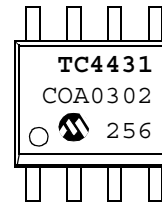
Example:



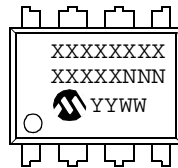
8-Lead SOIC (150 mil)



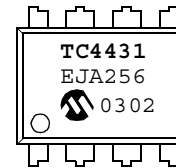
Example:



8-Lead CERDIP (300 mil)



Example:

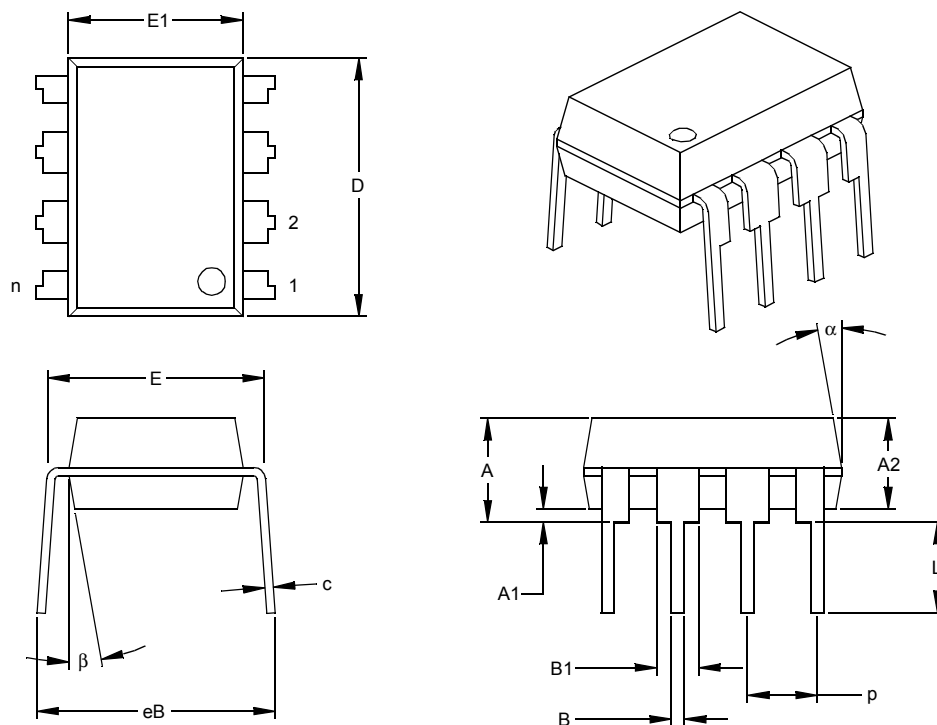


<b>Legend:</b>	XX...X	Customer specific information*
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
<b>Note:</b>	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

\* Standard OTP marking consists of Microchip part number, year code, week code, and traceability code.



## 8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



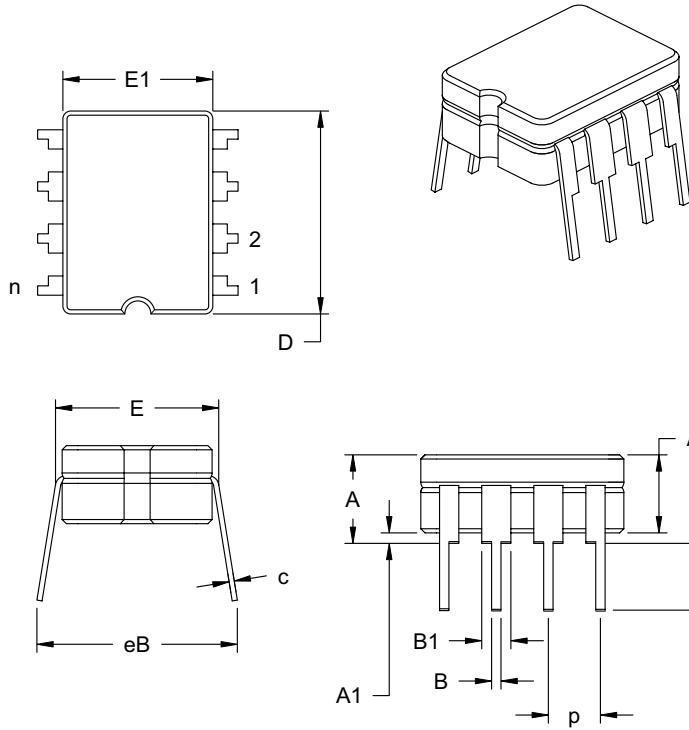
Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

\* Controlling Parameter  
 § Significant Characteristic

Notes:  
 Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.  
 JEDEC Equivalent: MS-001  
 Drawing No. C04-018

# TC4431/TC4432

## 8-Lead Ceramic Dual In-line (JA) – 300 mil (CERDIP)



Units		INCHES*			MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.160	.180	.200	4.06	4.57	5.08
Standoff §	A1	.020	.030	.040	0.51	0.77	1.02
Shoulder to Shoulder Width	E	.290	.305	.320	7.37	7.75	8.13
Ceramic Pkg. Width	E1	.230	.265	.300	5.84	6.73	7.62
Overall Length	D	.370	.385	.400	9.40	9.78	10.16
Tip to Seating Plane	L	.125	.163	.200	3.18	4.13	5.08
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.055	.065	1.14	1.40	1.65
Lower Lead Width	B	.016	.018	.020	0.41	0.46	0.51
Overall Row Spacing	eB	.320	.360	.400	8.13	9.15	10.16

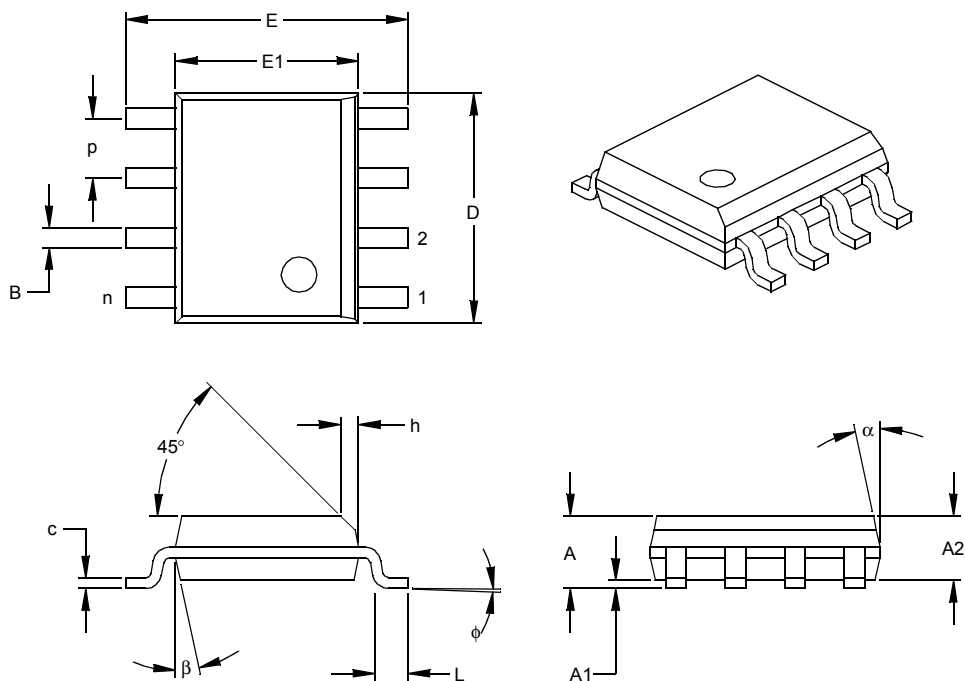
\*Controlling Parameter

JEDEC Equivalent: MS-030

Drawing No. C04-010

# TC4431/TC4432

## 8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



Dimension Limits	Units	INCHES*			MILLIMETERS		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

\* Controlling Parameter  
 § Significant Characteristic

**Notes:**

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

# TC4431/TC4432

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NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>
Device	Temperature Range	Package
Device:	TC4431: 1.5A High-Speed 30V MOSFET Driver, Inverting TC4432: 1.5A High-Speed 30V MOSFET Driver, Non Inverting	
Temperature Range:	C = 0°C to +70°C E = -40°C to +85°C	
Package:	JA = Ceramic Dual In-line (300 mil Body), 8-lead * OA = Plastic SOIC, (150 mil Body), 8-lead OA713 = Plastic SOIC, (150 mil Body), 8-lead (Tape and Reel) PA = Plastic DIP (300 mil Body), 8-lead * Offered in E-temp range only.	

**Examples:**

- a) TC4431COA: 1.5A MOSFET driver, SOIC package, 0°C to +70°C.
- b) TC4431EJA: 1.5A MOSFET driver, CERDIP package, -40°C to +85°C.
- a) TC4432CPA: 1.5A MOSFET driver, PDIP package, 0°C to +70°C.
- b) TC4432EPA: 1.5A MOSFET driver, PDIP package, -40°C to +85°C.

## Sales and Support

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2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site ([www.microchip.com](http://www.microchip.com))

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

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# TC4431/TC4432

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NOTES:

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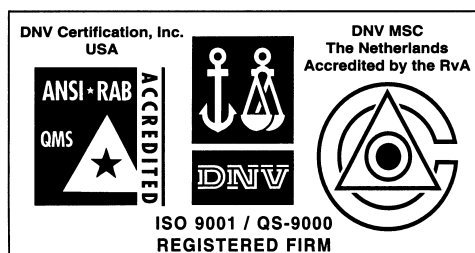
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# DSTEMP

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#### Phoenix

2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7966 Fax: 480-792-4338

#### San Jose

Microchip Technology Inc.  
2107 North First Street, Suite 590  
San Jose, CA 95131  
Tel: 408-436-7950 Fax: 408-436-7955

#### Toronto

6285 Northam Drive, Suite 108  
Mississauga, Ontario L4V 1X5, Canada  
Tel: 905-673-0699 Fax: 905-673-6509

### ASIA/PACIFIC

#### Australia

Microchip Technology Australia Pty Ltd  
Marketing Support Division  
Suite 22, 41 Rawson Street  
Epping 2121, NSW  
Australia  
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

#### China - Beijing

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Beijing Liaison Office  
Unit 915  
Bei Hai Wan Tai Bldg.  
No. 6 Chaoyangmen Beidajie  
Beijing, 100027, No. China  
Tel: 86-10-85282100 Fax: 86-10-85282104

#### China - Chengdu

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Chengdu Liaison Office  
Rm. 2401-2402, 24th Floor,  
Ming Xing Financial Tower  
No. 88 TIDU Street  
Chengdu 610016, China  
Tel: 86-28-86766200 Fax: 86-28-86766599

#### China - Fuzhou

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Fuzhou Liaison Office  
Unit 28F, World Trade Plaza  
No. 71 Wusi Road  
Fuzhou 350001, China  
Tel: 86-591-7503506 Fax: 86-591-7503521

#### China - Hong Kong SAR

Microchip Technology Hongkong Ltd.  
Unit 901-6, Tower 2, Metroplaza  
223 Hing Fong Road  
Kwai Fong, N.T., Hong Kong  
Tel: 852-2401-1200 Fax: 852-2401-3431

#### China - Shanghai

Microchip Technology Consulting (Shanghai)  
Co., Ltd.  
Room 701, Bldg. B  
Far East International Plaza  
No. 317 Xian Xia Road  
Shanghai, 200051  
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

#### China - Shenzhen

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Shenzhen Liaison Office  
Rm. 1812, 18/F, Building A, United Plaza  
No. 5022 Binhe Road, Futian District  
Shenzhen 518033, China  
Tel: 86-755-82901380 Fax: 86-755-8295-1393

#### China - Qingdao

Rm. B505A, Fullhope Plaza,  
No. 12 Hong Kong Central Rd.  
Qingdao 266071, China  
Tel: 86-532-5027355 Fax: 86-532-5027205

#### India

Microchip Technology Inc.  
India Liaison Office  
Marketing Support Division  
Divyasree Chambers  
1 Floor, Wing A (A3/A4)  
No. 11, O'Shaughnessey Road  
Bangalore, 560 025, India  
Tel: 91-80-2290061 Fax: 91-80-2290062

### Japan

Microchip Technology Japan K.K.  
Benex S-1 6F  
3-18-20, Shinyokohama  
Kohoku-Ku, Yokohama-shi  
Kanagawa, 222-0033, Japan  
Tel: 81-45-471-6166 Fax: 81-45-471-6122

### Korea

Microchip Technology Korea  
168-1, Youngbo Bldg. 3 Floor  
Samsung-Dong, Kangnam-Ku  
Seoul, Korea 135-882  
Tel: 82-2-554-7200 Fax: 82-2-558-5934

### Singapore

Microchip Technology Singapore Pte Ltd.  
200 Middle Road  
#07-02 Prime Centre  
Singapore, 188980  
Tel: 65-6334-8870 Fax: 65-6334-8850

### Taiwan

Microchip Technology (Barbados) Inc.,  
Taiwan Branch  
11F-3, No. 207  
Tung Hua North Road  
Taipei, 105, Taiwan  
Tel: 886-2-2717-7175 Fax: 886-2-2545-0139

### EUROPE

#### Austria

Microchip Technology Austria GmbH  
Durisolstrasse 2  
A-4600 Wels  
Austria  
Tel: 43-7242-2244-399  
Fax: 43-7242-2244-393

#### Denmark

Microchip Technology Nordic ApS  
Regus Business Centre  
Lautrup høj 1-3  
Ballerup DK-2750 Denmark  
Tel: 45-4420-9895 Fax: 45-4420-9910

#### France

Microchip Technology SARL  
Parc d'Activite du Moulin de Massy  
43 Rue du Saule Trapu  
Batiment A - ler Etage  
91300 Massy, France  
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

#### Germany

Microchip Technology GmbH  
Steinheilstrasse 10  
D-85737 Ismaning, Germany  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

#### Italy

Microchip Technology SRL  
Via Quasimodo, 12  
20025 Legnano (MI)  
Milan, Italy  
Tel: 39-0331-742611 Fax: 39-0331-466781

#### United Kingdom

Microchip Ltd.  
505 Eskdale Road  
Winnersh Triangle  
Wokingham  
Berkshire, England RG41 5TU  
Tel: 44-118-921-5869 Fax: 44-118-921-5820

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